## DSG-Ansys R&D Meeting Minutes

**Date:** May 5, 2022 **Time:** 14:00 to 15:00

Attendees: Aaron Brown, Pablo Campero, Brian Eng, Tyler Lemon, and Marc McMullen

## 1. <u>NPS thermal analysis</u>

Aaron Brown, Pablo Campero, and Marc McMullen

- 1. Modified simplified model; changed heat exchanger blocks with cylinders to represent the fans
  - Added four cylinders: two for top section and two for bottom section
  - Added electronic volume occupied by the PMTs, bases, and dividers using dimensions provided by NPS 3D model
- 2. In Design Modeler, combined electronics volume occupied by PMTs and electronic volume that encloses the electronics and cooling system (to the end of the box/frame plates)
- 3. Imported model to Fluent
  - Set material and configured solid and fluid domains
  - Implemented Turbulent Flow analysis (Model SST-K-omega)
  - Adding boundary conditions to set thermal heat transfer in model
  - Found another way to set the source of heat for volume in fluid domain but results do not make sense yet; more investigation required

## 2. <u>EIC-Beryllium Section Thermal Analysis</u>

Pablo Campero and Brian Eng

- 1. Completed thermal simulation for a model with 5 mm between the inner face of Si sensor L1 and the outer face of the Be pipe
  - Plotted results and presented in EIC Engineering meeting
  - The maximum temperature for Si sensor L1 is 31.23°C when air in annulus space is 18°C and 5 m/s
- 2. Noticed that temperature between models with 4 and 5 mm gap only drops about 4°C
- 3. Results for simulation at other temperatures followed the same trend



Fig.1. Maximum temperature for Si sensor L1 for model with 5 mm of separation